



Process Change Notification Form

PCN Number:	PCN_0274																			
Date of Notification:	15 Oct 2009																			
Cirrus Logic P/N(s):	CS8900A-CQ3Z, CS8900A-CQ3ZR, CS8900A-CQZ, CS8900A-CQZR, CS8900A-IQ3Z, CS8900A-IQ3ZR, CS8900A-IQZ, CS8900A-IQZR																			
Date PCN Effective:	01 Feb 2010																			
Reason for Change:	☐ Design /New Rev. ☐ Fab Site ☐ Fab Process ☐ Additional Fab Source ☐ Assembly Site ☐ Assembly Process ☒ Additional Assembly Source ☐ Other (specify):																			
Description of Change:	☐ Fix errata ☐ Yield enhancement ☐ Fix known bug ☐ Performance Improvement ☒ Other Addition of assembly site SCC. Summary of Bill of Material Change: <table border="1" style="width: 100%; border-collapse: collapse; margin-top: 10px;"> <tr> <td style="width: 33%;">100LQFP</td> <td style="width: 33%;">Current - SPIL</td> <td style="width: 33%;">New Site - SCC</td> </tr> <tr> <td>Mold Compound</td> <td>Sumitomo G700</td> <td>Sumitomo G700</td> </tr> <tr> <td>Die Attach</td> <td>Sumitomo 1033BF</td> <td>Ablestik 3230</td> </tr> <tr> <td>Wire</td> <td>1.0 mil Au</td> <td>1.0 mil Au</td> </tr> <tr> <td>Leadframe</td> <td>Cu 256 x 256 mil</td> <td>Cu 256 x 256 mil</td> </tr> <tr> <td>Finish</td> <td>Matte Sn, 100%</td> <td>Matte Sn, 100%</td> </tr> </table>		100LQFP	Current - SPIL	New Site - SCC	Mold Compound	Sumitomo G700	Sumitomo G700	Die Attach	Sumitomo 1033BF	Ablestik 3230	Wire	1.0 mil Au	1.0 mil Au	Leadframe	Cu 256 x 256 mil	Cu 256 x 256 mil	Finish	Matte Sn, 100%	Matte Sn, 100%
100LQFP	Current - SPIL	New Site - SCC																		
Mold Compound	Sumitomo G700	Sumitomo G700																		
Die Attach	Sumitomo 1033BF	Ablestik 3230																		
Wire	1.0 mil Au	1.0 mil Au																		
Leadframe	Cu 256 x 256 mil	Cu 256 x 256 mil																		
Finish	Matte Sn, 100%	Matte Sn, 100%																		
Cirrus Logic P/N Change:	☐ Yes, New Part Number: ☒ No																			
Pack Mark Change:	☒ Yes ☐ No If Yes, briefly explain: Two character field in Pack Mark used to denote assembly facility will change from "WA" to "BA", signifying StatsChipPac China. Country of origin will change from Taiwan to China.																			
Lot Effective Date:	Material manufactured with date code 1005 and later. <i>[Contact the area sales representative for availability of samples if applicable]</i>																			

Quality & Reliability impact:	***see pages below*** Qualification Data: ☒ Required ☐ Not Required
Datasheet Change Required?	☐ Yes ☒ No If Yes, briefly explain:
Software Change Required?	☐ Yes ☒ No If Yes, briefly explain:



RELIABILITY QUALIFICATION REPORT

Report Date: 9/30/2009

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Reliability Report: QRR090920

Subject/Purpose:

This is to qualify the Bill Of Materials change at STATSChipPAC (China) for the Pb-free 64 lead and 100 lead LQFP packages to Sumitomo G700 mold compound and Ablebond 3230 epoxy.

APPROVALS:

Rod Boutwell

Reliability Engineering

Results:

Qualification successful.

STATUS:

Complete - Pass

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/Sample)</u>
Precondition MSL-3	24HR 125 °C Bake	JESD22-A113	Precondition	1	0/154
QJ1842 (Similarity)	192HR 30°C/60%RH Soak		Precondition	2	0/231
QJ1844 (Similarity)	3 pass 260 °C Convection		Precondition	3	0/22
QJ1845 (Similarity)	reflow		Precondition	4	0/22
QJ1846			Precondition	5	0/77
QJ1847			Precondition	6	0/22
QJ1848			Precondition	7	0/231
QJ1849			Precondition	8	0/22
QJ1850 (Similarity)			Precondition	9	0/231
QJ1851 (Similarity)			Precondition		

Background Information:

Part #: CS8900A

Rev: H

Fab: MagnaChip (F)

Lead Finish: Pb-free

Package: 100LQFP

Assembly: STATSChipPAC (China)

Prepared by: Rod Boutwell

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<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/sample)</u>
THB	85 °C	JESD22-A101	1000 Hours	1	0/77
QJ1794 (Similarity)	85 %RH		1000 Hours	2	0/77
QJ1795 (Similarity)	5.25 Volts		1000 Hours	3	0/77
QJ1806	Static		1000 Hours	4	0/77
QJ1808 (Similarity)	85 °C		1000 Hours		
	85 %RH				
	5.0 Volts				
	Static				
Temperature Cycle cond. C	-65 °C	JESD22-A104	500 Cycles	1	0/77
QJ1842 (Similarity)	+150 °C		500 Cycles	2	0/77
QJ1844 (Similarity)	air to air		500 Cycles	3	0/77
QJ1849			500 Cycles	4	0/77
QJ1851 (Similarity)					
Tomography (CSAM)		J-STD-035	Post Temp Cycle	1	0/11
QJ1842 (Similarity)			Post Temp Cycle	2	0/11
QJ1844 (Similarity)			Post Precon	3	0/22
QJ1845 (Similarity)			Post Precon	4	0/22
QJ1846			Post Precon	5	0/22
QJ1848			Post Precon	6	0/11
QJ1849			Post Precon	7	0/22
QJ1850 (Similarity)			Post Temp Cycle	8	0/11
QJ1851 (Similarity)			Post Precon		

Background Information:

Part #: CS8900A	Rev: H	Fab: MagnaChip (F)	Lead Finish: Pb-free
Package: 100LQFP	Assembly: STATSChipPAC (China)		



Reliability Report: QRR090920

RELIABILITY QUALIFICATION REPORT

Report Date: 9/30/2009

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<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/sample)</u>
Autoclave/PPOT	121 °C	JESD22-A102	96 Hours	1	0/77
QJ1844 (Similarity)	15 psig		96 Hours	2	0/77
QJ1847	100% R.H.		96 Hours	3	0/77
QJ1849			96 Hours	4	0/77
QJ1851 (Similarity)					
Solderability	93 °C steam aging	JESD22-B102	Solderability	1	0/15
QJ1842 (Similarity)	8 Hours		Solderability	2	0/15
QJ1849	245 °C solder bath		Solderability	3	0/15
QJ1851 (Similarity)	5 Seconds				
HTSL (High Temp Storage Life)	150 °C	JESD22-A103	500 Hours	1	0/77
QJ1842 (Similarity)			1000 Hours	1	0/77
QJ1849			500 Hours	2	0/77
QJ1851 (Similarity)			1000 Hours	2	0/77
			500 Hours	3	0/77
			1000 Hours	3	0/77

Background Information:

Part #: CS8900A

Rev: H

Fab: MagnaChip (F)

Lead Finish: Pb-free

Package: 100LQFP

Assembly: STATSChipPAC (China)

Prepared by: Rod Boutwell

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Cirrus Logic -
Customer Quality

Cirrus Logic PCN administrator: _____

Digitally signed by Cirrus Logic - Customer Quality
DN: cn=Cirrus Logic - Customer Quality, c=US,
ou=Cirrus Logic Austin,
email=customer_quality@cirrus.com
Reason: All signatures on file
Date: 2009.11.04 09:52:58 -06'00'

Acknowledgement of Receipt of Notice:

Does customer waive PCN Effective Date? ☐ YES ☐ NO

Company Name: _____

Name (please print): _____ Title: _____

Signature: _____ Date: _____

Customer Representative is to obtain the customer acknowledgement/signature and return this notification to Cirrus Logic Corp. Quality, attn: PCN administrator at fax number (512) 851-4656

***NOTE: Lack of acknowledgement within 30 days of the date of notice, constitutes acceptance of change.
(Reference JEDEC Industry Standard: JESD-46)***